

ABSTRACT

An adhesive film (50) of the present invention is an adhesive film used when sealing an electronic component with a sealing material in a step of manufacturing an electronic apparatus to temporarily fix the electronic component, the adhesive film (50) including a base material layer (10), an adhesive resin layer (A) which is provided on a first surface (10A) side of the base material layer (10) and which is for temporarily fixing the electronic component, and an adhesive resin layer (B) which is provided on a second surface (10B) side of the base material layer (10) and of which the adhesive strength decreases according to an external stimulus, in which the adhesive resin layer (A) includes a polyvalent carboxylic acid ester-based plasticizer (X) and an adhesive resin (Y), and a content of the polyvalent carboxylic acid ester-based plasticizer (X) in the adhesive resin layer (A) is more than or equal to 0.7 parts by mass and less than or equal to 50 parts by mass with respect to 100 parts by mass of the adhesive resin (Y) included in the adhesive resin layer (A).

(Fig.1)